

Our technologies in SMT Manufacturing

Mühlbauer Laser Marking System

- Labelling area 360mm x 360mm
- Integrated turning unit

ASYS Cleaning Station

- Contactless, anti-static cleaning of unpopulated circuit boards
- Top-side cleaning



DEK Solder Paste Printer

- Simultaneous in/out PCB movement for reduced core cycle times
- Underside cleaning

ASMPT Solder Paste Inspection System

- Combines optical 2D and 3D measurement methods
- 3D on-the-fly compensation of PCB warping for high measurement accuracy

Fuji SMD Assembly System

- From prototype to mass production – assembly accuracy $\pm 0.050\text{mm}$ $\text{cpk} \geq 1.00$
- Assembly capacity of 120,000 contact units per hour

REHM Reflow Convection Soldering System

- High-efficiency reflow convection soldering system
- Flexible transport system with centre support

Omron Inline 3D AOI System

- Fully automated with a resolution of up to $15\mu\text{m}$
- 3D reconstruction using colour highlight and phase shift technology

Our technologies in THT Manufacturing

Conventional Manual Assembly

- Assembly using electronic visualisation
- Complete assembly of prototypes possible

SEHO Full-Tunnel Wave Soldering System

- Effective convection preheating for homogeneous and component-friendly assembly heating
- Freely configurable preheating range from 1800 mm to 3300 mm in length



SEHO Selective Soldering Unit

- Patented SYNCHRO concept enables sequential, parallel, or synchronous assembly processing
- Electromagnetic soldering units with innovative soldering nozzles for mini-wave and multi-wave processes

Manual Soldering Process

- Manual soldering according to IPC-A-610 Class 2, IPC-A-610 Class 3 available upon request
- Manual soldering according to WHMA-A-620

Schunk Stand-Alone Depaneling Machines

- Flexible creation of workpiece carriers using magnetic pins
- Shortest cycle times in a milling area of 500x600mm

Our technologies in the field of Assembly

Group Production

- Line production
- Cellular production

Assembly Processes

- Assembly of electronic components
- Pre-assembly and final assembly of complex modules

Different Assembly Technologies

- Press-fit technology & ultrasonic welding
- (Partially) automated assembly & screw-fastening technologies
- Robotic technology, casting and bonding processes



Our technologies in the field of Testing

ASMPT Solder Paste Insection System

- Combines optical 2D and 3D measurement methods
- 3D on-the-fly compensation of PCB warping for high measurement accuracy

Omron Inline 3D AOI System

- Fully automated with a resolution of up to 15µm
- 3D reconstruction using colour highlight and phase shift technology

Electrical Tests

- Boundary Scan
- In-circuit-test (e.g. using a needle bed adapter)

Functional Tests

- Conception and execution of customer-specific and complex functional tests
- Particular specialisation in high frequency testing using network and spectrum analysers



Testing Software

- Creation of testing software by in-house software engineers
- Individualised customer support for the implementation of project-specific testing requirements

Our Certifications

- DIN ISO 9001, DIN ISO 14001, DIN ISO 50001
- RoHS- and REACH-compliant production
- PCB production in accordance with IPC-A-610 class 2, IPC-A-610 class 3 on customer request

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